

General Description

The CSN2103 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The CSN2103 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_A=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	3	A
$I_D@T_A=70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	2.4	A
I_{DM}	Pulsed Drain Current ²	15	A
$P_D@T_A=25^\circ C$	Total Power Dissipation ³	2	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	85	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	24	$^\circ C/W$

Product Summary

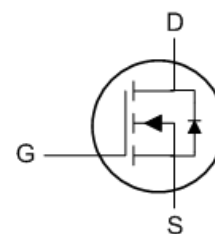
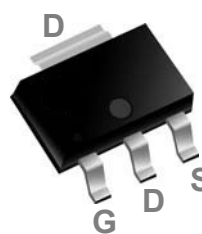


BVDSS	RDSON	ID
100V	75m Ω	3A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter
- Networking DC-DC Power System
- Power Tool Application

SOT223 Pin Configuration



Electrical Characteristics ($T_J=25\text{ }^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	100	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to $25\text{ }^\circ\text{C}$, $I_D=-1mA$	---	0.082	---	V/ $^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance ²	$V_{GS}=10V, I_D=3A$	---	60	75	m Ω
		$V_{GS}=4.5V, I_D=2A$	---	65	82	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	1.2	1.6	2.5	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-4.8	---	mV/ $^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=80V, V_{GS}=0V, T_J=25\text{ }^\circ\text{C}$	---	---	-1	μA
		$V_{DS}=80V, V_{GS}=0V, T_J=55\text{ }^\circ\text{C}$	---	---	-5	
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0V$	---	---	± 100	nA
gfs	Forward Transconductance	$V_{DS}=5V, I_D=3A$	---	5.8	---	S
R_g	Gate Resistance	$V_{DS}=0V, V_{GS}=0V, f=1MHz$	---	1.4	2.8	Ω
Q_g	Total Gate Charge (10V)	$V_{DS}=80V, V_{GS}=10V, I_D=3A$	---	40	56	nC
Q_{gs}	Gate-Source Charge		---	7.3	10.2	
Q_{gd}	Gate-Drain Charge		---	7	9.8	
$T_{d(on)}$	Turn-On Delay Time	$V_{DD}=50V, V_{GS}=10V, R_G=3.3\Omega, I_D=3A$	---	9.2	18.4	ns
T_r	Rise Time		---	22	40	
$T_{d(off)}$	Turn-Off Delay Time		---	41	82	
T_f	Fall Time		---	19.6	39	
C_{iss}	Input Capacitance	$V_{DS}=15V, V_{GS}=0V, f=1MHz$	---	2400	3360	pF
C_{oss}	Output Capacitance		---	100	140	
C_{rss}	Reverse Transfer Capacitance		---	82	115	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current ^{1,4}	$V_G=V_D=0V$, Force Current	---	---	3	A
I_{SM}	Pulsed Source Current ^{2,4}		---	---	15	A
V_{SD}	Diode Forward Voltage ²	$V_{GS}=0V, I_S=1A, T_J=25\text{ }^\circ\text{C}$	---	---	1.2	V
t_{rr}	Reverse Recovery Time	$I_F=3A, di/dt=100A/\mu s, T_J=25\text{ }^\circ\text{C}$	---	41	---	nS
Q_{rr}	Reverse Recovery Charge		---	25	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch²FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The power dissipation is limited by $150\text{ }^\circ\text{C}$ junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

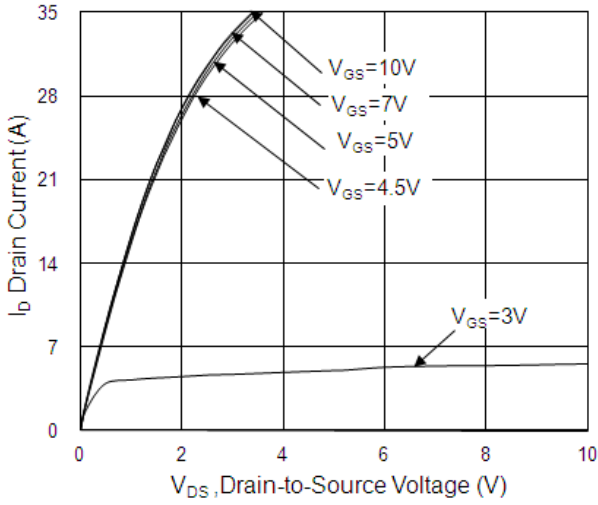


Fig.1 Typical Output Characteristics

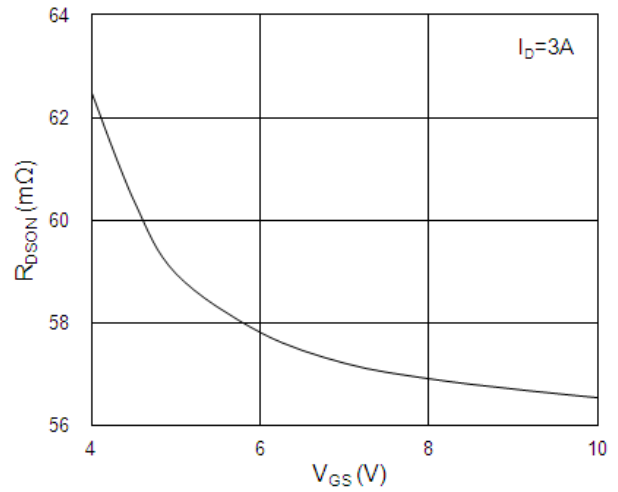


Fig.2 On-Resistance vs. Gate-Source

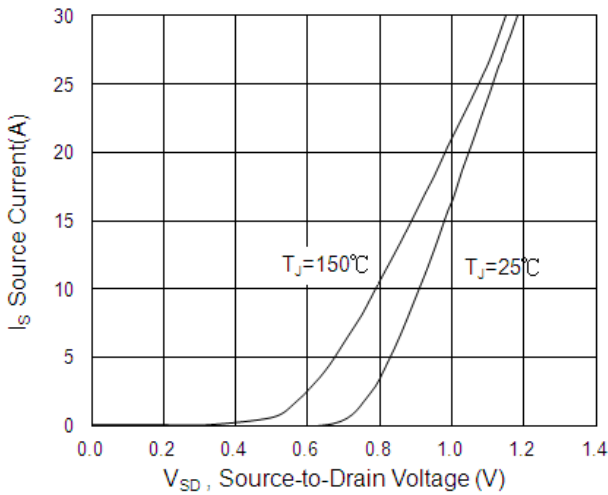


Fig.3 Forward Characteristics Of Reverse

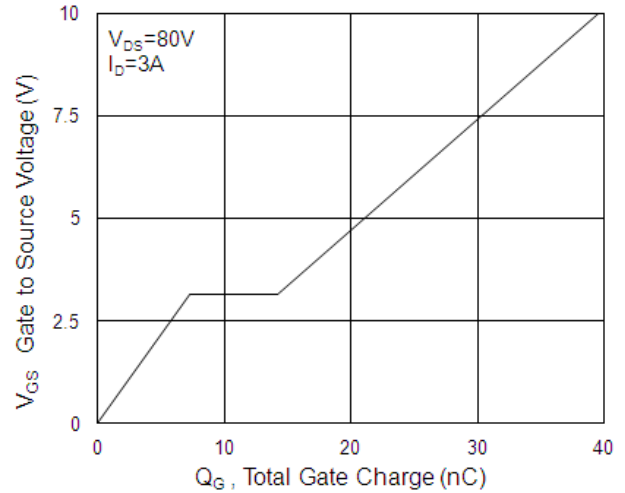


Fig.4 Gate-Charge Characteristics

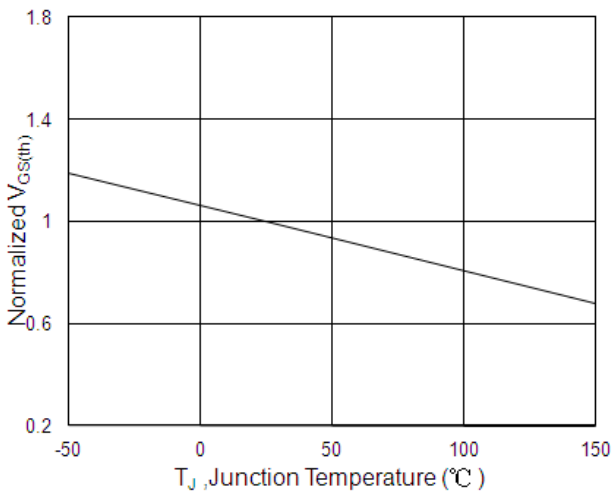


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

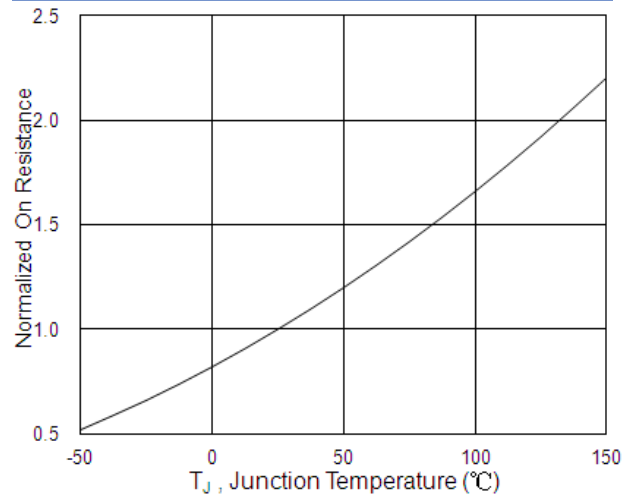


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

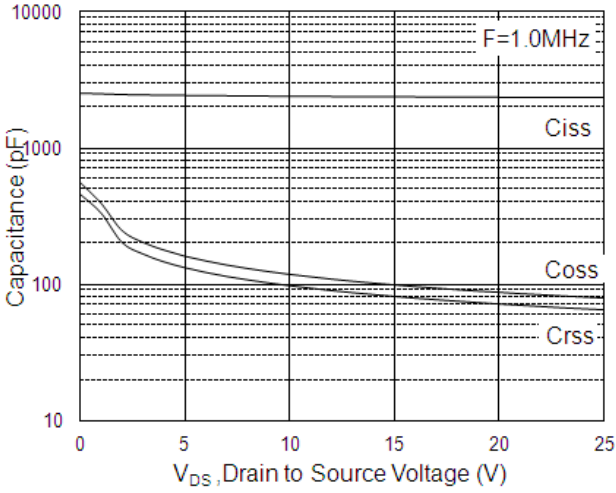


Fig.7 Capacitance

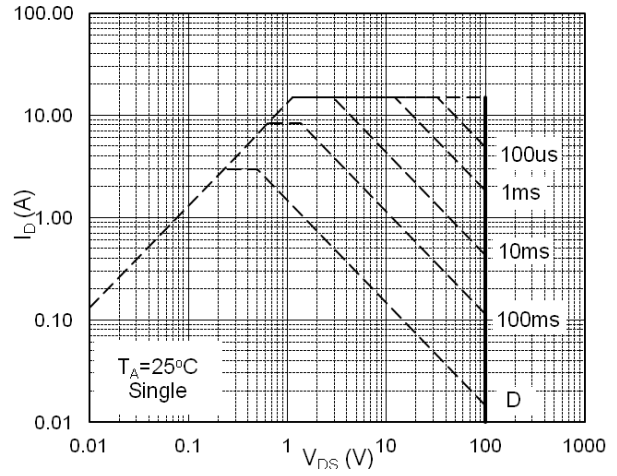


Fig.8 Safe Operating Area

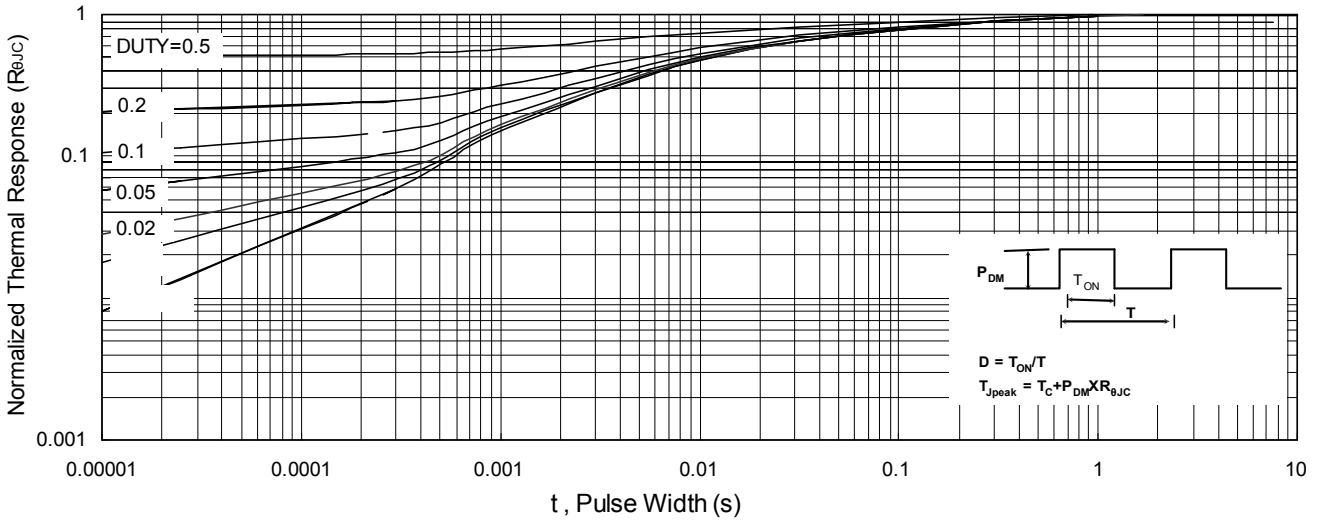


Fig.9 Normalized Maximum Transient Thermal Impedance

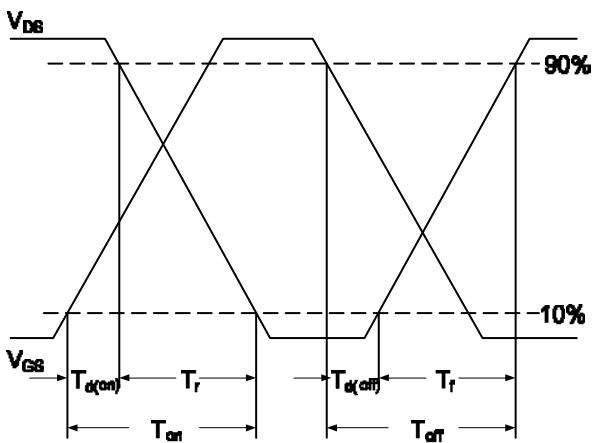


Fig.10 Switching Time Waveform

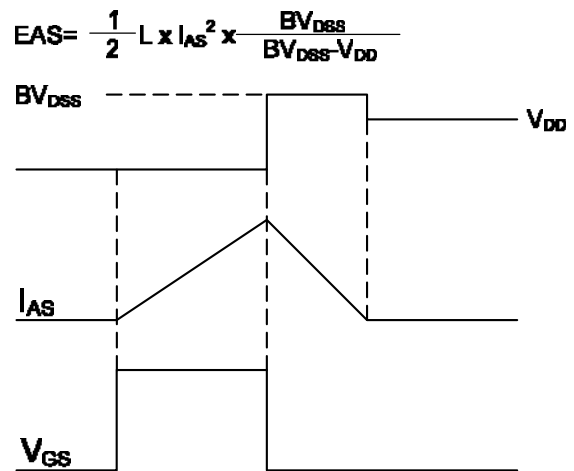
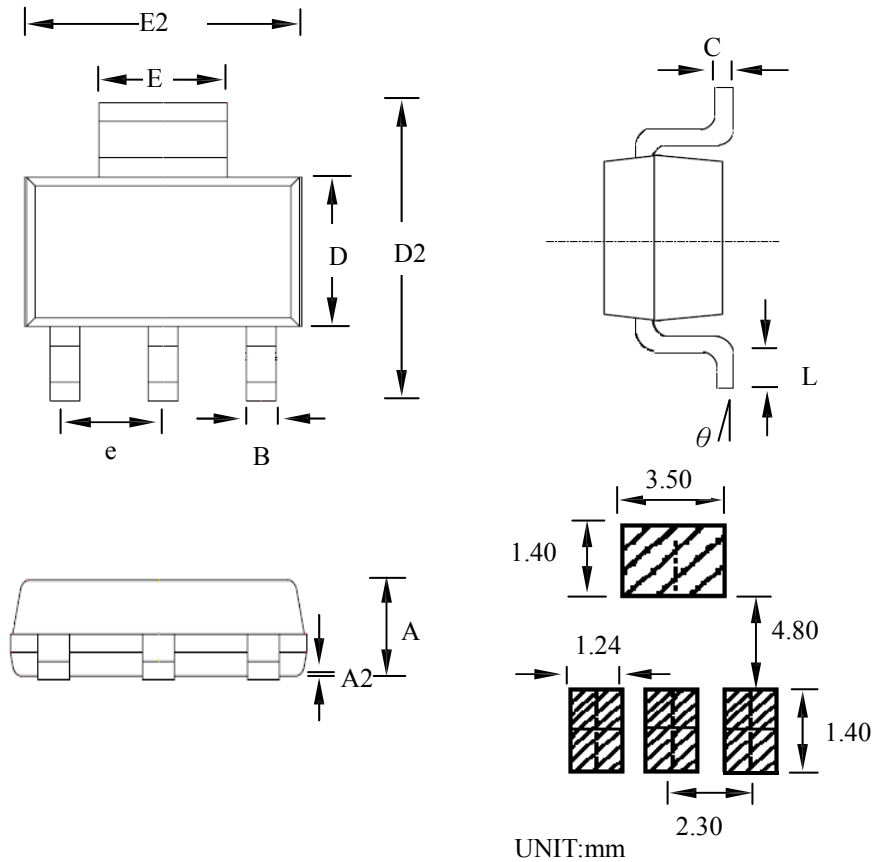


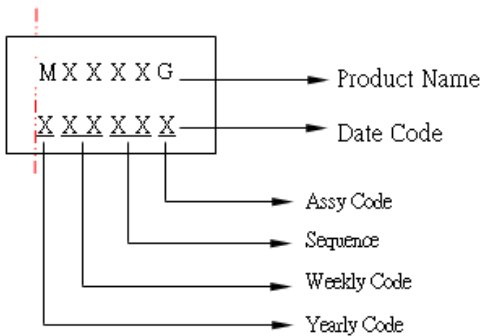
Fig.11 Unclamped Inductive Switching Waveform



UNIT:mm

LAND PATTERN RECOMMENDATION

MARKING



SYMBOLS	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	1.50	--	1.80	0.059	--	0.071
A2	0.02	--	0.10	0.001	--	0.004
B	0.60	0.70	0.84	0.024	0.028	0.033
C	0.23	--	0.35	0.009	--	0.014
D	3.30	3.50	3.70	0.130	0.138	0.146
D2	6.70	--	7.30	0.264	--	0.287
E	2.90	3.00	3.10	0.114	0.118	0.122
E2	6.30	6.50	6.70	0.248	0.256	0.264
L	0.75	0.90	1.00	0.030	0.035	0.039
θ	0°	--	10°	0°	--	10°
e	--	2.30	--	--	0.091	--